



### **General Description**

The WSD40190DN56G advanced SGT technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

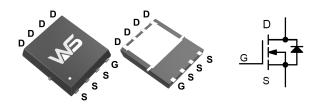
### **Product Summery**

BVDSS	RDSON	ID
40V	1.25mΩ	190A

# **Applications**

- Battery protection
- Load switch
- Uninterruptible power supply

# **DFN5X6-8L Pin Configuration**



# **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	190	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	130	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	400	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	259	mJ
I <sub>AS</sub>	Avalanche Current	72	Α
P <sub>D</sub> @T <sub>c</sub> =25℃	Total Power Dissipation⁴	96	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

#### **Thermal Data**

Symbol	Parameter	Тур. Мах.		Unit	
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		55	°C/W	
R <sub>eJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		1.3	°C/W	



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.043		V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		1.25	1.6	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		1.8	2.7	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0		2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-6.94		mV/℃
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			2	- uA
		$V_{DS}$ =32V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			10	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	VDS=10V,ID=15A		70		S
Qg	Total Gate Charge	V <sub>DS</sub> =20V , V <sub>GS</sub> =10V , I <sub>D</sub> =20A		78		nC
Qg	Total Gate Charge	V <sub>DS</sub> =20V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =20A		35		nC
$Q_gs$	Gate-Source Charge			15		
$Q_{gd}$	Gate-Drain Charge			9		
T <sub>d(on)</sub>	Turn-On Delay Time			22		
T <sub>r</sub>	Rise Time	$V_{DD}$ =20V , $V_{GEN}$ =10V , $R_G$ =16 $\Omega$ , $I_D$ =1A ,RL=20 $\Omega$ .		12		- ns
$T_{d(off)}$	Turn-Off Delay Time			86		
T <sub>f</sub>	Fall Time			84		
C <sub>iss</sub>	Input Capacitance			5400		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		1200		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			180		
Is	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			87	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =20A , T <sub>J</sub> =25℃			1.3	V

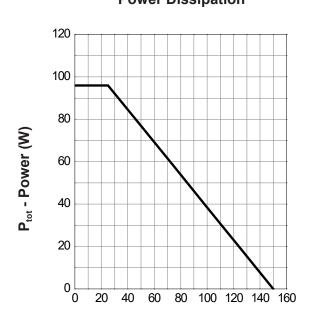
### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =20V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =72A
- 4.The power dissipation is limited by 150  $^{\circ}\mathrm{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



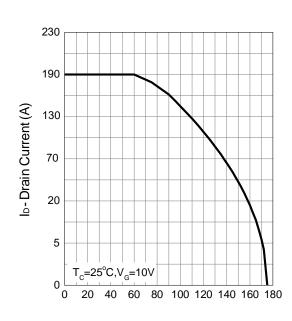
# **Typical Characteristics**

# Power Dissipation



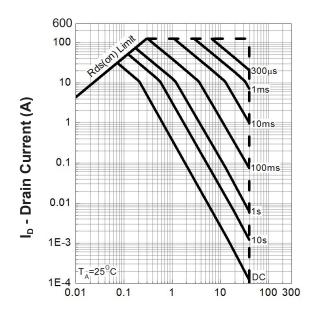
T<sub>c</sub> - Case Temperature (°C)

#### **Drain Current**



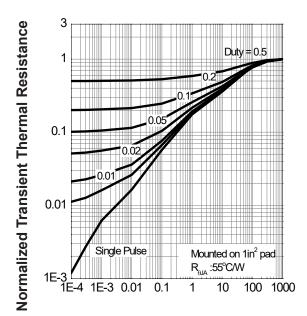
T<sub>j</sub>- Junction Temperature (°C)

# **Safe Operation Area**



V<sub>DS</sub> - Drain - Source Voltage (V)

# **Thermal Transient Impedance**

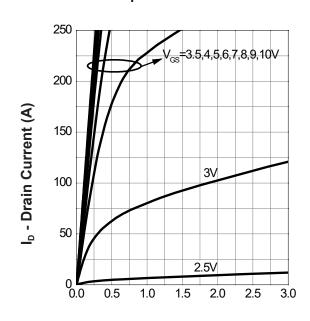


**Square Wave Pulse Duration (sec)** 



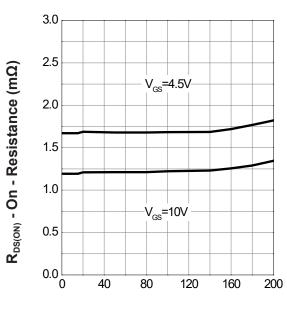
# **Typical Characteristics**

# **Output Characteristics**



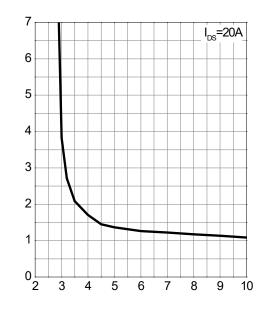
V<sub>DS</sub> - Drain - Source Voltage (V)

### **Drain-Source On Resistance**



I<sub>D</sub> - Drain Current (A)

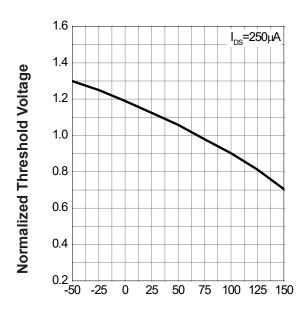
# **Gate-Source On Resistance**



R<sub>DS(ON)</sub> - On - Resistance (mΩ)

V<sub>GS</sub> - Gate - Source Voltage (V)

# **Gate Threshold Voltage**

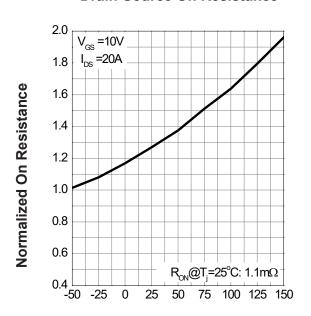


T<sub>i</sub> - Junction Temperature (°C)



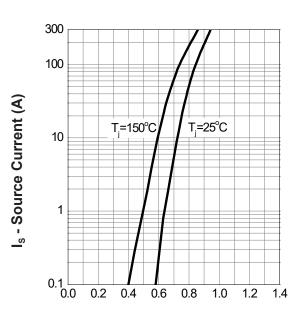
# **Typical Characteristics**

### **Drain-Source On Resistance**



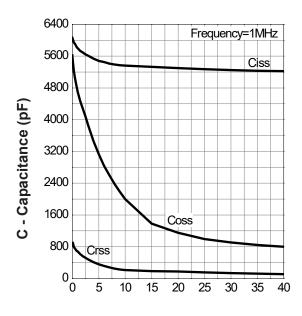
T<sub>i</sub> - Junction Temperature (°C)

## **Source-Drain Diode Forward**



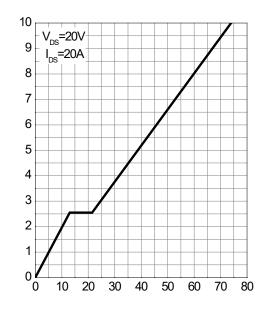
V<sub>SD</sub> - Source - Drain Voltage (V)

## Capacitance



V<sub>DS</sub> - Drain-Source Voltage (V)

### **Gate Charge**



Q<sub>G</sub> - Gate Charge (nC)

V<sub>GS</sub> - Gate-source Voltage (V)



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